

09/985,898
SON-0519US

Please add the following new claims:

16. The surface acoustic wave filter of claim 9, wherein the comb electrode patterns that are formed on a chip substrate further comprise a high-resistance pattern that is formed to surround a peripheral portion of the chip substrate on an upper surface of the substrate.

17. The surface acoustic wave filter according to claim 16, wherein the comb electrode patterns are set at the same potential to each other and connected to the high-resistance pattern.

18. The surface acoustic wave filter according to claim 9, further comprising:
a dummy electrode pattern formed on the upper surface of the chip substrate so as to be adjacent to the comb electrode patterns.

19. A surface acoustic wave filter, comprising:
a plurality of comb electrode patterns formed on a first surface of a chip substrate, wherein the comb electrode patterns serve as an input signal electrode terminal, an output signal electrode terminal, and a ground electrode terminal; and
a coating film of a conductive material, wherein the coating film covers at least part of a second surface of the chip substrate and wherein the coating film is connected to the ground electrode terminal on the first surface of the chip substrate.

09/985,898
SON-0519US

20. The surface acoustic wave filter of claim 19, wherein the coating film is connected to the ground electrode terminal by an extension of the coating film conductive material from the coating film on the second surface to the ground electrode terminal on the first surface.

21. The surface acoustic wave filter of claim 19, wherein the input signal electrode terminal, the output signal electrode terminal, and the ground electrode terminal are formed on a package which accommodates the filter and are each connected to the comb electrode patterns through a conductive material.

22. A surface acoustic wave filter, comprising:
a plurality of comb electrode patterns formed on a chip substrate;
a high-resistance pattern formed on the chip substrate; and
a plurality of patterns formed to connect to the high-resistance pattern with the respective electrode patterns.

23. A surface acoustic wave filter, comprising:
a plurality of pairs of comb electrode patterns formed on an upper surface of a chip substrate; and
a dummy electrode pattern formed on the upper surface of the chip substrate so as to be adjacent and connected to the comb electrode patterns.